SCBS025C - SEPTEMBER 1988 - REVISED APRIL 1994

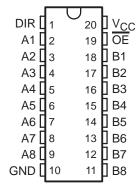
- State-of-the-Art BiCMOS Design Substantially Reduces Standby Current
- Outputs Have Undershoot-Protection Circuitry
- Power-Up High-Impedance State
- Buffered Control Inputs to Reduce DC Loading Effects
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Plastic and Ceramic 300-mil DIPs (J, N)

#### description

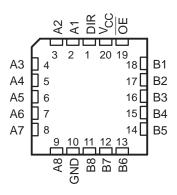
The 'BCT640 bus transceiver is designed for asynchronous communication between data buses. These devices transmit data from the A bus to the B bus or from the B bus to the A bus depending upon the level at the direction-control (DIR) input. The output-enable  $(\overline{OE})$  input can be used to disable the device so that the buses are effectively isolated.

The SN54BCT640 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74BCT640 is characterized for operation from 0°C to 70°C.

SN54BCT640 . . . J OR W PACKAGE SN74BCT640 . . . DW OR N PACKAGE (TOP VIEW)



SN54BCT640 . . . FK PACKAGE (TOP VIEW)

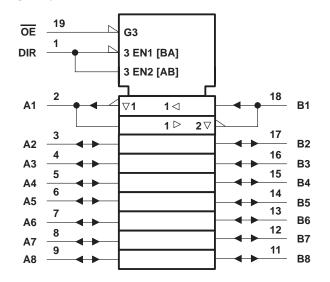


#### **FUNCTION TABLE**

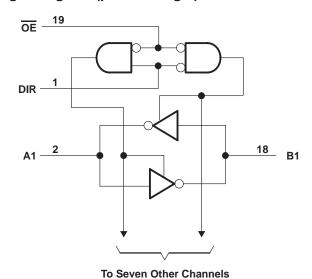
INP	UTS	ODED ATION					
ŌĒ	DIR	OPERATION					
L	L	B data to A bus					
L	Н	A data to B bus					
Н	Χ	Isolation					

SCBS025C - SEPTEMBER 1988 - REVISED APRIL 1994

# logic symbol†



## logic diagram (positive logic)



# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V <sub>CC</sub>	– 0.5 V to 7 V
Input voltage range: Control inputs (see Note 1)	– 0.5 V to 7 V
I/O ports (see Note 1)	– 0.5 V to 5.5 V
Voltage range applied to any output in the disab	ed or power-off state, $V_{\mbox{O}}$ – 0.5 V to 5.5 V
Voltage range applied to any output in the high	rate, V <sub>O</sub> – 0.5 V to V <sub>CC</sub>
Input clamp current, I <sub>IK</sub>	
Current into any output in the low state: SN54B6	T640 96 mA
SN74B0	T640 128 mA
Operating free-air temperature range: SN54B6	T640 – 55°C to 125°C
SN74B	T6400°C to 70°C
Storage temperature range	– 65°C to 150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

SCBS025C - SEPTEMBER 1988 - REVISED APRIL 1994

## recommended operating conditions

			SN	54BCT6	40	SN	74BCT6	40	LINUT	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage		4.5	5	5.5	4.5	5	5.5	V	
VIH	High-level input voltage		2			2			V	
V <sub>IL</sub>	Low-level input voltage			8.0			0.8	V		
I <sub>IK</sub>	Input clamp current			-18			-18	mA		
	I Pale Level and and annual	A port			-3			-3	0	
ІОН	High-level output current	B port			-12			-15	mA	
	Laur laural autout aumant	A port			20			24		
lOL	Low-level output current	B port			48			64	mA	
TA	Operating free-air temperature		-55		125	0		70	°C	

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER		TEST CONDITIONS		SN	54BCT6	40	SN74BCT640			LINUT	
P/	ARAMETER	TES	T CONDITIONS	MIN	TYP†	MAX	MIN	TYP <sup>†</sup>	MAX	UNIT	
VIK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V	
	A and	V 45V	I <sub>OH</sub> = -1 mA	2.5	3.4		2.5	3.4			
	A port	V <sub>CC</sub> = 4.5 V	$I_{OH} = -3 \text{ mA}$	2.4	3.3		2.4	3.3			
∨он			$I_{OH} = -3 \text{ mA}$	2.4	3.3		2.4	3.3		V	
	B port	V <sub>CC</sub> = 4.5 V	$I_{OH} = -12 \text{ mA}$	2	3.2						
			$I_{OH} = -15 \text{ mA}$				2	3.1			
	A	V 45V	I <sub>OL</sub> = 20 mA		0.3	0.5					
	A port	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 24 mA					0.35	0.5	v	
VOL	Phort	V 45V	I <sub>OL</sub> = 48 mA		0.38	0.55				V	
	B port	V <sub>CC</sub> = 4.5 V	$I_{OL} = 64 \text{ mA}$					0.42	0.55		
	A or B port	.,	V 55V			1			1	4	
I <sub>I</sub>	Control inputs	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 5.5 V			0.1			0.1	mA	
. +	A or B port	.,	V 07V			70			70	•	
¹IH <sup>‡</sup>	Control inputs	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 2.7 V			20			20	μΑ	
. +	A or B port	V 55V	V 05V			-0.6			-0.6	0	
I <sub>IL</sub> ‡	Control inputs	V <sub>CC</sub> = 5.5 V,	$V_{I} = 0.5 V$			-0.65			-0.65	mA	
	A port	.,		-60		-150	-60		-150		
IOS <sup>§</sup> B port	$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 0	-100		-225	-100		-225	mA		
ICCL	A to B	V <sub>CC</sub> = 5.5 V			53	84		53	94	mA	
ICCH	A to B	V <sub>CC</sub> = 5.5 V			23	37		23	41	mA	
ICCZ		V <sub>CC</sub> = 5.5 V			4	10		4	11	mA	

<sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C. ‡ For I/O ports, the parameters I<sub>IH</sub> and I<sub>IL</sub> include the off-state output current. § Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

# SN54BCT640, SN74BCT640 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS SCBS025C - SEPTEMBER 1988 - REVISED APRIL 1994

## switching characteristics (see Note 2)

PARAMETER	FROM (INPUT)	-		C = 5 V = 50 p = 500 9 2 = 500 9 4 = 25°C	F, Ω, Ω,	$V_{CC}$ = 4.5 V to 5.5 V, $C_L$ = 50 pF, R1 = 500 Ω, R2 = 500 Ω, $T_A$ = MIN to MAX $\dagger$				UNIT
			′BCT640			SN54BCT640		SN74BCT640		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	4 5	B or A	0.5	3.6	5.6	0.5	7	0.5	6.5	ns
t <sub>PHL</sub>	A or B		0.5	1.9	3.4	0.5	3.8	0.5	3.7	
<sup>t</sup> PZH	ŌĒ	A D	3.1	6.4	8.9	2.6	10.5	2.6	10.2	
tPZL	OE	A or B	4.1	6.9	9.5	3.5	12.3	3.5	10.7	ns
<sup>t</sup> PHZ	ŌĒ	A or B	1.9	5	7.9	1.4	12.2	1.4	10.2	ns
tPLZ			A of B	1.8	4.3	6.8	1.5	8.3	1.5	7.8

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



10-Jun-2022 www.ti.com

#### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9075201M2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9075201M2A SNJ54BCT 640FK	Samples
5962-9075201MRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9075201MR A SNJ54BCT640J	Samples
5962-9075201MSA	ACTIVE	CFP	W	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9075201MS A SNJ54BCT640W	Samples
SN74BCT640DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT640	Samples
SN74BCT640N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74BCT640N	Samples
SN74BCT640NSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT640	Samples
SNJ54BCT640FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9075201M2A SNJ54BCT 640FK	Samples
SNJ54BCT640J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9075201MR A SNJ54BCT640J	Samples
SNJ54BCT640W	ACTIVE	CFP	W	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9075201MS A SNJ54BCT640W	Samples

<sup>(1)</sup> The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design. PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

# PACKAGE OPTION ADDENDUM

www.ti.com 10-Jun-2022

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF SN54BCT640, SN74BCT640:

Catalog: SN74BCT640

Military: SN54BCT640

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

# **PACKAGE MATERIALS INFORMATION**

www.ti.com 5-Jan-2022

# TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74BCT640NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1

www.ti.com 5-Jan-2022



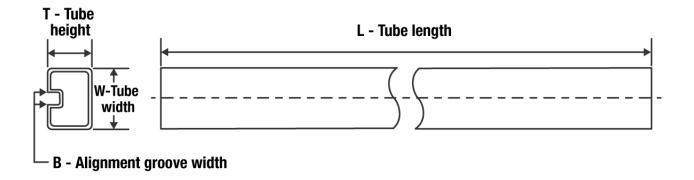
#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74BCT640NSR	SO	NS	20	2000	367.0	367.0	45.0

# PACKAGE MATERIALS INFORMATION

www.ti.com 5-Jan-2022

#### **TUBE**



\*All dimensions are nominal

7 til diritoriororio di o riorimidi								
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9075201M2A	FK	LCCC	20	1	506.98	12.06	2030	NA
SN74BCT640DW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74BCT640N	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54BCT640FK	FK	LCCC	20	1	506.98	12.06	2030	NA

# W (R-GDFP-F20)

# CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.

  D. Index point is provided on cap for terminal identification only.

  E. Falls within Mil—Std 1835 GDFP2—F20



# FK (S-CQCC-N\*\*)

# LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



## **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



# 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# N (R-PDIP-T\*\*)

# PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



#### IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2022, Texas Instruments Incorporated